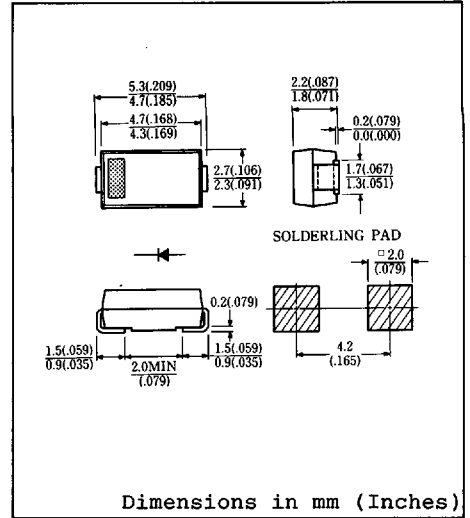


FEATURES

- Miniature Size, Surface Mount Device
- High Surge Capability
- Low Forward Voltage Drop
- Low Reverse Leakage Current
- Packaged in 12mm Tape and Reel
- Not Rolling During Assembly



Dimensions in mm (Inches)

Approx. Net Weight : 0.06 Grams

MAXIMUM RATINGS

Voltage Rating	TYPE	EC10DS1	EC10DS2	EC10DS4	EC10DS6	Unit
	Symbol					
Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	v
Non-Repetitive Peak Reverse Voltage	V_{RSM}	250	400	600	---	v
Electrical Rating	Symbol	Condition			Rating	Unit
Average Rectified Output Current	I_O	180° sinusoidal wave conduction Ceramic substrate mounted* $T_a = 25^\circ\text{C}$			1.0	A
		180° sinusoidal wave conduction Glass-Epoxy substrate mounted* $T_a = 25^\circ\text{C}$			0.74	
RMS Forward Current	$I_{F(RMS)}$				1.57	A
Peak One-cycle Forward Surge Current	I_{FSM}	50Hz half sine wave, non-repetitive			25	A
Operating Frequency	f				1,000	Hz
Operating Junction Temperature Range	T_{jw}				-40 to 150	°C
Storage Temperature Range	T_{stg}				-40 to 150	°C

ELECTRICAL & THERMAL CHARACTERISTICS

Characteristics	Symbol	Test Condition	Max.	Unit
Peak Forward Voltage	V_{FM}	$I_{FM} = 1.0A$ $T_j = 25^\circ\text{C}$	1.1	V
Peak Reverse Current	I_{RM}	$V_{RM} = V_{RRM}$ $T_j = 25^\circ\text{C}$	10	μA
Thermal Resistance, junction to ambient	$R_{th(j-a)}$	Ceramic substrate mounted*	108	°C/W
		Glass-Epoxy substrate mounted*	157	

* Substrate Soldering Land = 2 x 2mm

FIG.1-FORWARD VOLTAGE
VS. FORWARD CURRENT

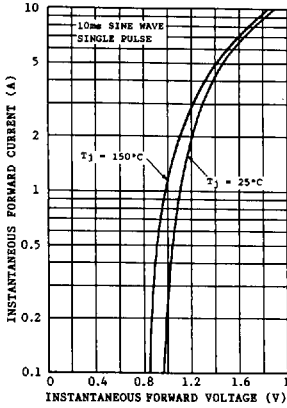


FIG.2-AVERAGE FORWARD POWER
DISSIPATION

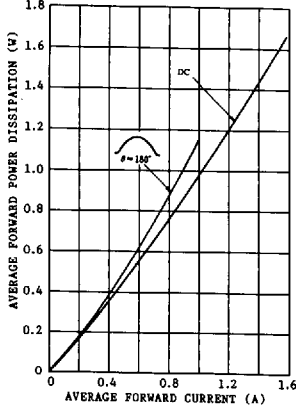


FIG.3- FIG.5-AVERAGE FORWARD CURRENT
VS. AMBIENT TEMPERATURE

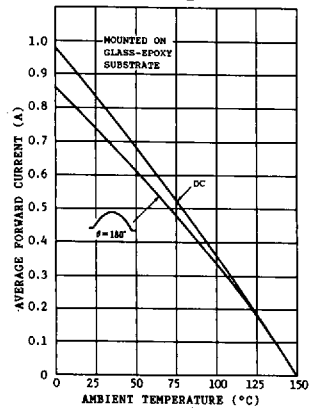


FIG.4-AVERAGE FORWARD CURRENT
VS. AMBIENT TEMPERATURE

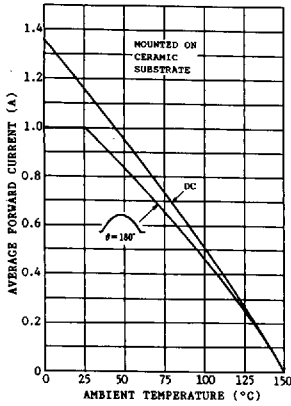


FIG.5-AVERAGE FORWARD CURRENT
VS. AMBIENT TEMPERATURE

